

Material Composition Declaration

iS15M2R5S1T

Company Name:	iDEAL Semiconductor Devices, Inc.
Quality Contact:	Deo Laranang
Contact email:	dlaranang@idealsemi.com
Part Weight:	748.77 mg

Material	Composition	CAS No.	% of weight	Weight (mg)
Wafer	Silicon	7440-21-3	100	7.17
Lead Frame	Cu	7440-50-8	BAL	512.79
	Fe	7439-89-6	0.05~0.15	
	P	7723-14-0	0.015~0.040	
Solder	Pb	7439-92-1	92.3~92.7	17.7600
	Sn	7440-31-5	4.9~5.1	
	Ag	7440-22-4	2.4~2.6	
Wire	Al	7429-90-5	>99.99	13.7250
	Ni	7440-02-0	<60ppm	
	Si	7440-21-3	<10ppm	
	Fe	7439-89-6	<3ppm	
	Mg	7439-95-4	<3ppm	
	Cu	7440-50-8	<3ppm	
	B	7440-42-8	<1ppm	
	Ag	7440-22-4	<1ppm	
	Mn	7439-96-5	<1ppm	
	Ca	7440-70-2	<1ppm	
	Cr	7440-47-3	<1ppm	
	Al	7429-90-5	≥99.99	0.0945
	The others	-	≤0.01	
Mold Compound	Epoxy resin	Trade Secret	5 - 10	192.25
	Phenol Resin	Trade Secret	1 - 5	
	Silica(Amorphous) A	60676-86-0	70 - 90	
	Silica(Amorphous) B	7631-86-9	10 - 20	
	Carbon black	1333-86-4	0.1 - 1	
Plating	Tin	7440-31-5	99.90	4.9800
	Other		<0.1	
Total Weight				748.7695



Note: The substance content disclosed herewith is approximate and is based on engineering calculations. Statements are based on our present knowledge and may be subject to change at any time due to technical requirements and development. iDEAL Semiconductor may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.